127-20A/B

PAD PRINTABLE CONDUCTIVE INK

DESCRIPTION: 127-20 is a two component, pad printable, conductive ink/coating for application by pad printing, dipping and syringe dispensing. The product features excellent adhesion to pretreated polyethylene, and polypropylene, as well as to some varieties of pretreated polytetrafluoroethylene. This material will also adhere to Polyurethane, polyamide, melamine, phenolic resins, metal, and glass substrates. Unlike conventional conductive materials, this product is very resistant to abrasion, scratching, flexing and creasing. Some applications for 127-20 include, but are not limited to, emi/rfi shielding, flexible circuits, and membrane switches.

TYPICAL PROPERTIES:

Viscosity (cps) 10,000 – 14,000
Filler Silver
Percent Filler (cured) > 88
Sheet Resistance (Ω/sq/mil, MAX)
   5 min. @ 125°C 0.050
   30 min. @ 125°C 0.025
Crease Resistance Excellent
Hydrolytic Stability Excellent
Useful Temperature Range (°C) -55 to +200
Mix ratio (by weight) 100 (Part A)
                      5 (Part B)
Pot Life, Min. (room temperature) 7 Hrs.

CURE SCHEDULE:

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<tr>
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<th>22°C</th>
<th>125°C</th>
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<tr>
<td>Handling</td>
<td>25 min.</td>
<td>3 min.</td>
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<td>Full Cure</td>
<td>12-16 days</td>
<td>2 hrs.</td>
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SUGGESTED HANDLING & CURING: Prior to use, be certain to mix well to re-suspend filler. Mix parts A, and B as prescribed above. Further thinning may be accomplished by adding small amounts of CMI thinner 113-39 or for slower drying 114-20, and/or 114-28 for drying rates between the two. End user is advised to experimentally determine temperature and time best suited for individual applications.

Shelf life Part B: 6 months at 25°C in sealed containers.
Please Note: Part B is sensitive to moisture/humidity and should be tightly re-sealed immediately after using.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to suitability in a particular application or possible infringements on patents.